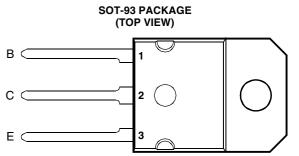
BD250, BD250A, BD250B, BD250C PNP SILICON POWER TRANSISTORS

BOURNS®

- Designed for Complementary Use with the BD249 Series
- 125 W at 25°C Case Temperature
- 25 A Continuous Collector Current
- 40 A Peak Collector Current
- Customer-Specified Selections Available



Pin 2 is in electrical contact with the mounting base.

absolute maximum ratings at 25°C case temperature (unless otherwise noted)

RATING			VALUE	UNIT	
	BD250		-55		
	BD250A	N/	-70	v	
Collector-emitter voltage ($R_{BE} = 100 \Omega$)	BD250B	V _{CER}	-90	v	
	BD250C		-115		
	BD250		-45		
Collector-emitter voltage (I _C = -30 mA)	BD250A	N/	-60	v	
	BD250B	V _{CEO}	-80	v	
	BD250C		-100		
Emitter-base voltage			-5	V	
Continuous collector current			-25	A	
Peak collector current (see Note 1)		I _{CM}	-40	A	
Continuous base current			-5	A	
Continuous device dissipation at (or below) 25°C case temperature (see Note 2)			125	W	
Continuous device dissipation at (or below) 25°C free air temperature (see Note 3)			3	W	
Unclamped inductive load energy (see Note 4)			90	mJ	
Operating junction temperature range			-65 to +150	°C	
Storage temperature range			-65 to +150	°C	
Lead temperature 3.2 mm from case for 10 seconds	T _{stg} T _L	250	°C		

NOTES: 1. This value applies for $t_p \leq 0.3$ ms, duty cycle $\leq 10\%.$

2. Derate linearly to 150°C case temperature at the rate of 1 W/°C.

3. Derate linearly to 150°C free air temperature at the rate of 24 mW/°C.

4. This rating is based on the capability of the transistor to operate safely in a circuit of: L = 20 mH, $I_{B(on)}$ = -0.4 A, R_{BE} = 100 Ω , $V_{BE(off)}$ = 0, R_S = 0.1 Ω , V_{CC} = -20 V.

PRODUCT INFORMATION

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electrical characteristics at 25°C case temperature

PARAMETER			TEST CONDITIO	DNS	MIN	I TYP MAX		UNIT
V _{(BR)CEO}	Collector-emitter breakdown voltage	I _C = -30 mA (see Note 5)	I _B = 0	BD250 BD250A BD250B BD250C	-45 -60 -80 -100			v
I _{CES}	Collector-emitter cut-off current	$V_{CE} = -55 V$ $V_{CE} = -70 V$ $V_{CE} = -90 V$ $V_{CE} = -115 V$		BD250 BD250A BD250B BD250C			-0.7 -0.7 -0.7 -0.7	mA
I _{CEO}	Collector cut-off current	V _{CE} = -30 V V _{CE} = -60 V	I _B = 0 I _B = 0	BD250/250A BD250B/250C			-1 -1	mA
I _{EBO}	Emitter cut-off current	V _{EB} = -5 V	l _C = 0				-1	mA
h _{FE}	Forward current transfer ratio	$V_{CE} = -4 V$ $V_{CE} = -4 V$ $V_{CE} = -4 V$	I _C = -15 A	(see Notes 5 and 6)	25 10 5			
V _{CE(sat)}	Collector-emitter saturation voltage	-	I _C = -25 A	(see Notes 5 and 6)			-1.8 -4	V
V _{BE}	Base-emitter voltage	$V_{CE} = -4 V$ $V_{CE} = -4 V$	I _C = -15 A I _C = -25 A	(see Notes 5 and 6)			-2 -4	V
h _{fe}	Small signal forward current transfer ratio	V _{CE} = -10 V	I _C = - 1A	f = 1 kHz	25			
h _{fe}	Small signal forward current transfer ratio	V _{CE} = -10 V	I _C = -1 A	f = 1 MHz	3			

NOTES: 5. These parameters must be measured using pulse techniques, $t_p = 300 \ \mu s$, duty cycle $\leq 2\%$.

6. These parameters must be measured using voltage-sensing contacts, separate from the current carrying contacts.

thermal characteristics

PARAMETER			ТҮР	MAX	UNIT
R _{θJC}	Junction to case thermal resistance			1	°C/W
R _{θJA}	Junction to free air thermal resistance			42	°C/W

resistive-load-switching characteristics at 25°C case temperature

PARAMETE	R	TEST CONDITIONS [†]			ТҮР	MAX	UNIT
t _{on} Turn-on tim	le I _C = -5 A	I _{B(on)} = -0.5 A	$I_{B(off)} = 0.5 A$		0.2		μs
t _{off} Turn-off tim	e V _{BE(off)} = 5 V	$R_L = 5 \Omega$	$t_p = 20 \ \mu s, \ dc \le 2\%$		0.4		μs

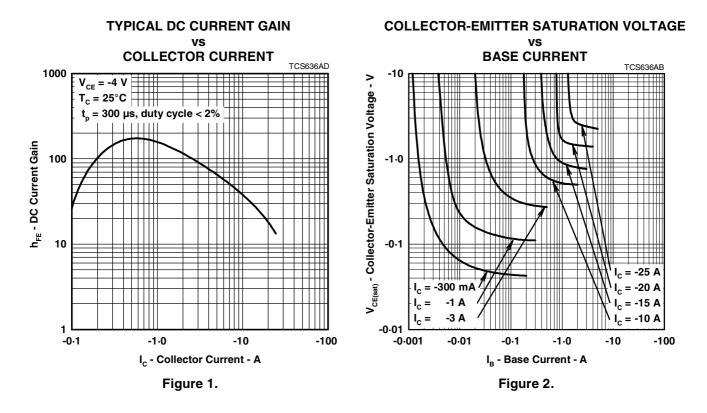
[†] Voltage and current values shown are nominal; exact values vary slightly with transistor parameters.

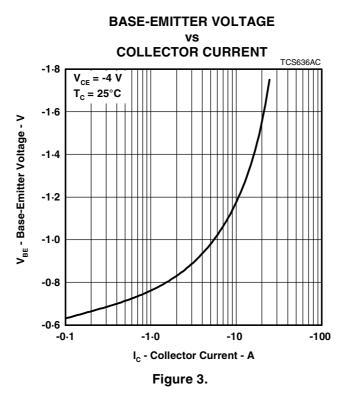




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TYPICAL CHARACTERISTICS

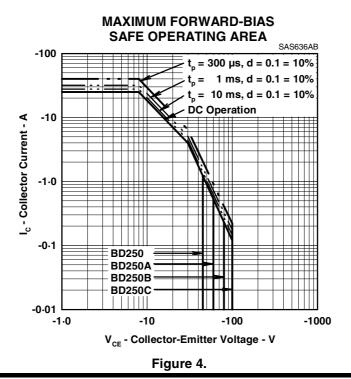




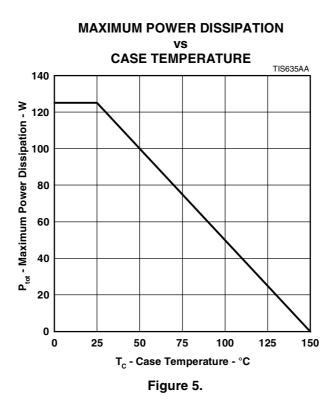
PRODUCT INFORMATION

JUNE 1973 - REVISED SEPTEMBER 2002 Specifications are subject to change without notice.

MAXIMUM SAFE OPERATING REGIONS





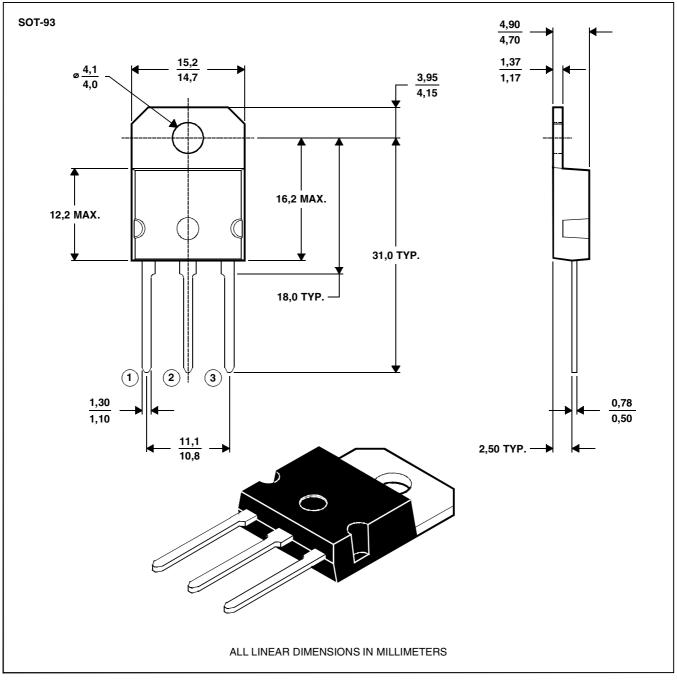


MECHANICAL DATA

SOT-93

3-pin plastic flange-mount package

This single-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.



NOTE A: The centre pin is in electrical contact with the mounting tab.

MDXXAW

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